Small Signal MOSFET

20 V, Dual N-Channel, SC-88 **ESD Protection**

Features

- Small Footprint (2 x 2 mm)
- Low Gate Charge N-Channel Device
- ESD Protected Gate
- Same Package as SC-70 (6 Leads)
- Pb-Free Packages are Available

Applications

- Load Power switching
- Li-Ion Battery Supplied Devices
- Cell Phones, Media Players, Digital Cameras, PDAs
- DC-DC Conversion

MAXIMUM RATINGS (T_J = 25°C unless otherwise stated)

Param	Symbol	Value	Unit			
Drain-to-Source Voltage			V_{DSS}	20	V	
Gate-to-Source Voltage)		V _{GS}	±12	V	
Continuous Drain Current	Steady State	T _A = 25°C	I _D	0.63	Α	
(Based on R _{θJA})	State	T _A = 85°C		0.46		
Power Dissipation	Steady	T _A = 25°C	P _D	0.27	W	
(Based on R _{θJA})	State	T _A = 85°C		0.14		
Continuous Drain Current	Steady State	T _A = 25°C	I _D	0.91	Α	
(Based on R _{θJL})	State	T _A = 85°C		0.65		
Power Dissipation	Steady	T _A = 25°C		0.55	W	
(Based on R _{θJL})	State	T _A = 85°C	P _D	0.29		
Pulsed Drain Current t ≤10 μs			I _{DM}	±1.2	Α	
Operating Junction and	T _J , T _{STG}	-55 to 150	°C			
Continuous Source Curr	Is	0.63	Α			
Lead Temperature for So (1/8" from case for 10 s)	TL	260	°C			

THERMAL RESISTANCE RATINGS (Note 1)

Parameter	Symbol	Тур	Max	Units
Junction-to-Ambient - Steady State	$R_{\theta JA}$	400	460	°C/W
Junction-to-Lead (Drain) - Steady State	$R_{\theta JL}$	194	226	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Surface mounted on FR4 board using 1 oz Cu area = 0.9523 in sq.

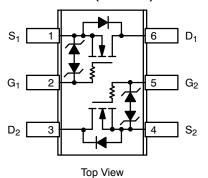


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http://onsemi.com

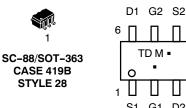
V _{(BR)DSS}	R _{DS(on)} Typ	I _D Max		
	0.22 Ω @ 4.5 V			
20 V	0.32 Ω @ 2.5 V	0.775 A		
	0.51 Ω @ 1.8 V			

SC-88 (SOT-363)



MARKING DIAGRAM & PIN ASSIGNMENT

G1 D2



TD = Device Code М = Date Code = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise stated)

Parameter	Symbol	Test Cond	dition	Min	Тур	Max	Unit
OFF CHARACTERISTICS	•		•		-	-	-
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		20	27		V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J				22		mV/ °C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V, V _D	_{OS} = 16 V			1.0	μΑ
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _G	_S = ±12 V			10	μΑ
ON CHARACTERISTICS (Note 2)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_{D}$	= 250 μΑ	0.6	0.92	1.5	V
Gate Threshold Temperature Coefficient	V _{GS(TH)} /T _J				-2.1		mV/ °C
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 4.5 V, I _E	o = 0.63 A		0.29	0.375	Ω
		V _{GS} = 2.5 V, I _E	o = 0.40 A		0.36	0.445	
Forward Transconductance	9FS	V _{DS} = 4.0 V, I _D = 0.63 A			2.0		S
CHARGES AND CAPACITANCES	•					•	
Input Capacitance	C _{ISS}	$V_{GS} = 0 \text{ V, f} = 1.0 \text{ MHz,}$ $V_{DS} = 20 \text{ V}$			33	46	pF
Output Capacitance	C _{OSS}				13	22	
Reverse Transfer Capacitance	C _{RSS}				2.8	5.0	
Total Gate Charge	Q _{G(TOT)}	$V_{GS} = 4.5 \text{ V}, V_{DS} = 10 \text{ V},$ $I_D = 0.63 \text{ A}$			1.3	3.0	nC
Threshold Gate Charge	Q _{G(TH)}				0.1		
Gate-to-Source Charge	Q _{GS}				0.2		7
Gate-to-Drain Charge	Q_{GD}		Ī		0.4		
SWITCHING CHARACTERISTICS (No	ote 3)					•	
Turn-On Delay Time	td _(ON)				0.083		μS
Rise Time	tr	VGS = 4.5 V. Vr	nn = 10 V.		0.227		
Turn-Off Delay Time	td _(OFF)	V_{GS} = 4.5 V, V_{DD} = 10 V, I_{D} = 0.5 A, R_{G} = 20 Ω			0.786		
Fall Time	tf				0.506		
DRAIN-SOURCE DIODE CHARACTE	RISTICS	•	•		•	•	•
Forward Diode Voltage	V _{SD}	V _{GS} = 0 V,	T _J = 25°C		0.76	1.1	V
		I _S =0.23 A	T _J = 125°C		0.63		7
Reverse Recovery Time	t _{RR}	$V_{GS} = 0 \text{ V, } dI_S/dt = 100 \text{ A/}\mu\text{s,}$ $I_S = 0.63 \text{ A}$			0.410		μS

Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.
 Switching characteristics are independent of operating junction temperatures.

TYPICAL PERFORMANCE CURVES (T $_{J}$ = 25°C unless otherwise noted)

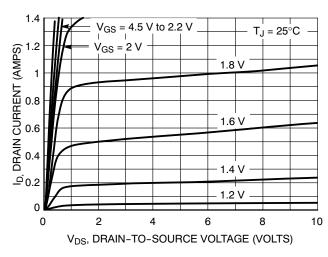


Figure 1. On-Region Characteristics

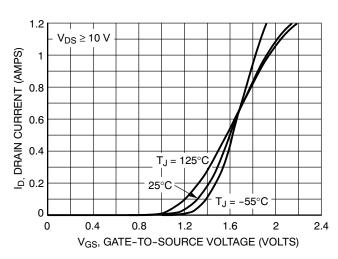


Figure 2. Transfer Characteristics

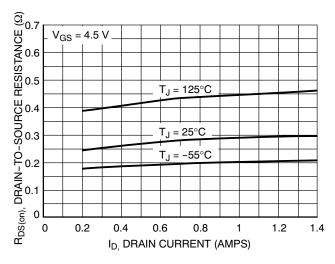


Figure 3. On-Resistance vs. Drain Current and Temperature

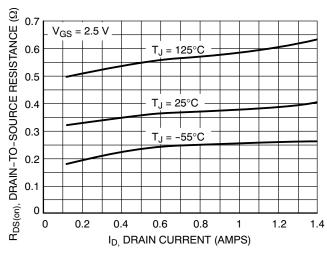


Figure 4. On-Resistance vs. Drain Current and Temperature

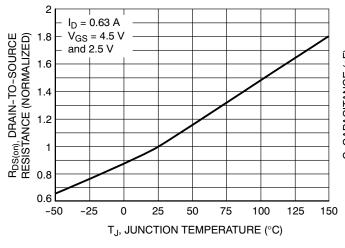


Figure 5. On-Resistance Variation with Temperature

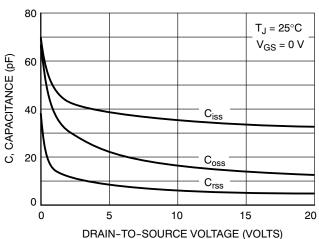
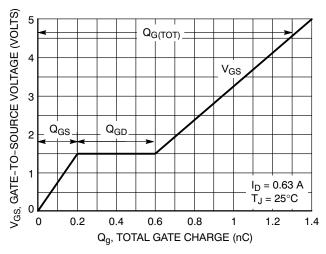
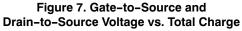


Figure 6. Capacitance Variation

TYPICAL PERFORMANCE CURVES (T_J = 25°C unless otherwise noted)





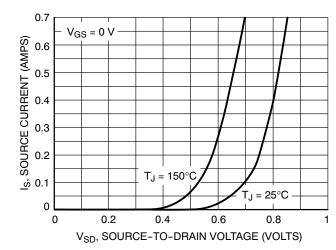


Figure 8. Diode Forward Voltage vs. Current

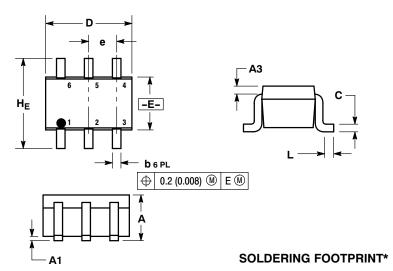
ORDERING INFORMATION

Device	Package	Shipping [†]		
NTJD4401NT1	SC-88	3000 / Tape & Reel		
NTJD4401NT1G	SC-88 (Pb-Free)	3000 / Tape & Reel		
NTJD4401NT2	SC-88	3000 / Tape & Reel		
NTJD4401NT2G	SC-88 (Pb-Free)	3000 / Tape & Reel		
NTJD4401NT4	SC-88	10,000 / Tape & Reel		
NTJD4401NT4G	SC-88 (Pb-Free)	10,000 / Tape & Reel		

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

SC-88/SC70-6/SOT-363 CASE 419B-02 ISSUE W



NOTES

- DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
- 419B-01 OBSOLETE, NEW STANDARD 419B-02.

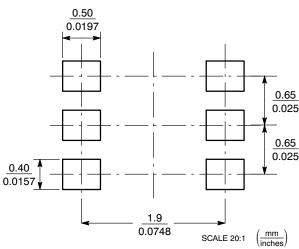
	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.80	0.95	1.10	0.031	0.037	0.043	
A1	0.00	0.05	0.10	0.000	0.002	0.004	
А3	0.20 REF			0.008 REF			
b	0.10	0.21	0.30	0.004	0.008	0.012	
O	0.10	0.14	0.25	0.004	0.005	0.010	
D	1.80	2.00	2.20	0.070	0.078	0.086	
Е	1.15	1.25	1.35	0.045	0.049	0.053	
е	0.65 BSC			0.026 BSC			
٦	0.10	0.20	0.30	0.004	0.008	0.012	
Н	2.00	2.10	2.20	0.078	0.082	0.086	

STYLE 26:

- PIN 1. SOURCE 1 2. GATE 1

 - 3. DRAIN 2 4. SOURCE 2

 - 5. GATE 2 6. DRAIN 1



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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